



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Fee et al.

**Serial No.:** 10/729,180

**Filed:** December 5, 2003

**For:** QUAD FLAT NO LEAD (QFN) GRID  
ARRAY PACKAGE, METHOD OF  
MAKING AND MEMORY MODULE AND  
COMPUTER SYSTEM INCLUDING SAME

**Confirmation No.:** 8592

**Examiner:** T. Le

**Group Art Unit:** 2827

**Attorney Docket No.:** 2269-4738.2US  
(00-1113.02/US)

**NOTICE OF EXPRESS MAILING**

Express Mail Mailing Label Number: EL995989967US

Date of Deposit with USPS: April 10, 2006

Person making Deposit: Timothy Palfreyman

**COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE**

Mail Stop Issue Fee  
Commissioner for Patents  
PO Box 1450  
Alexandria, VA 22313-1450

Sir:

Prior to the issuance of the Notice of Allowability, the Examiner stated that:

Claims 1-13 include allowable subject matter since the prior art made of record and considered pertinent to the applicant's disclosure does not teach or suggest the claimed limitations. Casper (U.S. Patent No. 6,184,067), Casper (U.S. Patent No. 6,587,892, and others, does not teach the claimed invention having a recess in the dielectric encapsulant between at least one conductive element of the at least a first set of conductive elements and at least one adjacent conductive element of the at least one other set of conductive elements.

And further stated:

Claims 1-6, 11-20 include allowable subject matter since the prior art made of record and considered pertinent to the applicant's disclosure does not teach or suggest the claimed limitations. Keown et al. (U.S. Patent No. 5,286,656), and others, does not teach the claimed invention having a dielectric encapsulant formed over the semiconductor die and defining the outer lateral periphery of the integrated circuit package, the dielectric encapsulant extending at least partially laterally about the plurality of conductive elements and leaving an outer surface of each conductive element exposed; and a recess in the dielectric encapsulant between at least one conductive element of the at least a first set of conductive elements and at least one adjacent conductive element of the at least one other set of conductive elements.

Applicants note that the independent claims as allowed include other and different language than that particularly cited by the Examiner, and the allowed dependent claims include other and further features and elements. Accordingly, the scope of the claims must be determined from the literal language of each as a whole, as well as equivalents thereof.

Respectfully submitted,



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Date: April 10, 2006  
BBJ/dlm:slm

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